

Abstract

[Problem]

To provide a technology capable of reducing an occurrence of pickup errors.

5 [Solution]

A semiconductor manufacturing device includes: a wafer holding table that holds a wafer ring holding a dicing tape attached to a wafer divided into dies; a peeling unit that assists in picking up the die from the dicing tape; and a
10 control unit configured to set peeling conditions that are operation conditions of the peeling unit on the basis of peripheral information which is a die arrangement information in a peripheral region of a die to be picked up.

[Selected Drawing] FIG. 13